

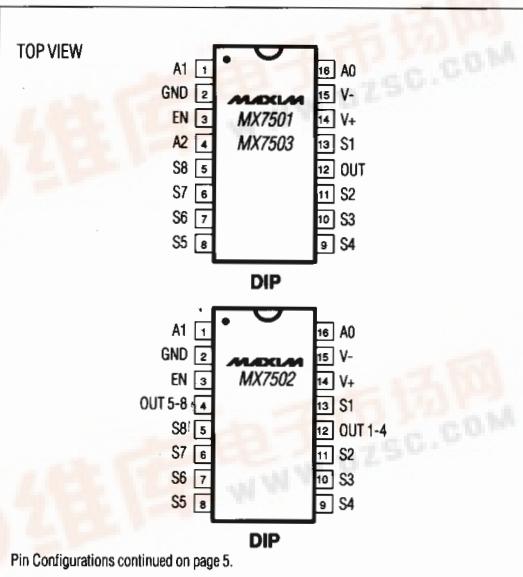
19-2863; Rev 0; 7/90

MAXIM**Low-Power,
Monolithic, CMOS Analog Multiplexers****General Description**

Maxim's MX7501/7502/7503 are low-power, monolithic, CMOS analog multiplexers. The MX7501 is a single-ended, 8-channel (1-of-8) multiplexer, while the MX7502 is a differential, 4-channel (2-of-8) multiplexer. The MX7503 is identical to the MX7501, except the enable logic is inverted (channels are on with Enable low). These devices are plug-in upgrades for the industry-standard "7501/7502/7503": the MX7501/7502/7503 consume significantly less power (6mW Max) and offer a wider operating range of power-supply voltages (a single supply of +10V to +30V, or dual supplies of $\pm 5V$ to $\pm 18V$). The MX7501/7502/7503 also feature Maxim's standard latchup-proof CMOS construction, and they are both TTL and CMOS compatible.

Applications

- Control Systems
- Data Logging Systems
- Aircraft Heads-Up Displays
- Data Acquisition Systems
- Signal Routing
- Portable Equipment

Pin Configurations**Features**

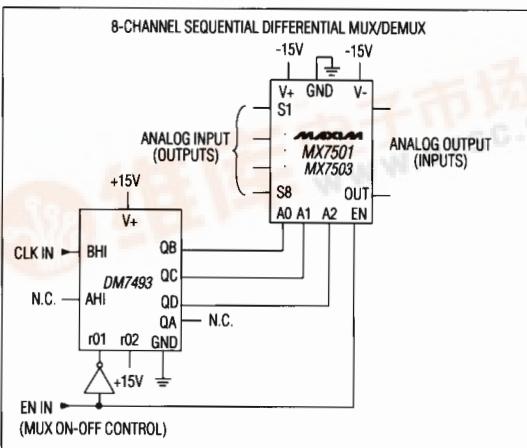
- ◆ Drop-In Upgrade for Industry-Standard "7501/7502/7503"
- ◆ Low-Power Consumption: 6mW Max
- ◆ Operable with $\pm 4.5V$ to $\pm 18V$ Supplies
- ◆ Latchup-Proof Construction
- ◆ Symmetrical, Bidirectional Operation
- ◆ TTL and CMOS Compatible Logic Inputs
- ◆ Monolithic, Low-Power CMOS Design

Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE
MX7501JN	0°C to +70°C	16 Plastic DIP
MX7501KN	0°C to +70°C	16 Plastic DIP
MX7501C/D*	0°C to +70°C	Dice
MX7501JQ	-40°C to +85°C	16 CERDIP
MX7501KQ	-40°C to +85°C	16 CERDIP
MX7501SQ	-55°C to +125°C	16 CERDIP
MX7501SE*	-55°C to +125°C	20 LCC

* For Dice, Plastic Leadless Chip Carrier (PLCC), Ceramic Leadless Chip Carrier (LCC) and Ceramic Sidebrazed (Ceramic SB), contact factory for availability.

Ordering information continued on page 6.

MX7501/7502/7503**Typical Operating Circuit****MAXIM****Call toll free 1-800-998-8800 for free samples or literature.****Maxim Integrated Products 1**

Low-Power, Monolithic, CMOS Analog Multiplexers

ABSOLUTE MAXIMUM RATINGS

V+ to GND	+18V	Power Dissipation (Any Package)	
V- to GND	-18V	Up to +50°C	1000mW
V Between Any Switch Terminals (Note 1)	25V	Derate above +50°C by	10mW/°C
Digital Input Voltage Range	V+ to GND	Operating Temperature	
Max Overvoltage at VOUT (Vs)	V-, V+	MX750_JN/KN/C/D	0°C to +70°C
Switch Current (Is, Continuous 1 Channel)	20mA	MX750_JQ/KQ	-40°C to +85°C
Switch Current (Is, Surge 1 Channel, 1ms Duration, 10% Duty Cycle)	35mA	MX750_SQ/SE	-55°C to +125°C
		Storage Temperature	-65°C to +150°C

Note 1: Do not apply voltages higher than V+ and V- to any other terminal, especially when V- = V+ = 0V, all other pins should be at 0V.

Note 2: The digital control inputs are diode protected; however, permanent damage may occur on unconnected units under high-energy electrostatic fields. Keep unused units in conductive foam at all times.

Stresses listed under "Absolute Maximum Ratings" may be applied (one at a time) to devices without resulting in permanent damage. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V+ = +15V, V- = -15V, GND = 0V, unless otherwise noted.)

PARAMETER	SYMBOL	VERSION (Note 3)	SWITCH CONDITION	TEST CONDITIONS	+25°C			OVER SPECIFIED TEMP. RANGE			UNITS
					MIN	TYP	MAX	MIN	TYP	MAX	
ANALOG SWITCH											
Drain-Source On Resistance	r _{DS(ON)}	J, K, S	On	V _S = ±10V, I _S = 1mA	180	300		450			Ω
	r _{DS(ON)} vs. V _S	All	On	V _S = ±10V, I _S = 1mA	15						%
Tempco of On Resistance	r _{DS(ON)} vs. Temp.	All	On	V _S = 0V, I _S = 1mA				0.5			%/°C
	Δr _{DS(ON)} Between Switches	All	On	V _S = 0V, I _S = 1mA	4						%
Difference in On Resistance Between Channels	Δr _{DS(ON)} vs. Temp. Between Switches	All	On	V _S = 0V, I _S = 1mA				0.05			%/°C
	Source-Off Leakage Current	I _{S(OFF)}	J, K	Off	V _S = -10V, V _D = +10V and V _S = +10V, V _D = -10V "Enable Low"	±0.2	2	±50			nA
			S	Off			±0.5		±50		
Drain-Off Leakage Current	I _{D(OFF)}	J, K	Off	V _S = -10V, V _D = +10V and V _S = +10V, V _D = -10V "Enable Low"	±10			±250			nA
		S	Off		±5			±250			
		J, K	Off		±5			±125			
		S	Off		±3			±125			
Channel-On Leakage Current I _{D(ON)} -I _S (Any Switch On)	I _{D(ON)}	J, K	On	V _S = 0	±12			±300			nA
		S	On	V _S = 0	±5.5			±300			
		J, K	On	V _S = 0	±7			±175			
		S	On	V _S = 0	±3.5			±175			

MX7501/7502/7503

Low-Power, Monolithic, CMOS Analog Multiplexers

ELECTRICAL CHARACTERISTICS (continued)

(V₊ = +15V, V₋ = -15V, GND = 0V, unless otherwise noted.)

PARAMETER	SYMBOL	VERSION (Note 3)	SWITCH CONDITION	TEST CONDITIONS	+25°C			OVER SPECIFIED TEMP. RANGE			UNITS
					MIN	TYP	MAX	MIN	TYP	MAX	
DIGITAL CONTROL											
Address-Input Threshold (Low)	V _{INL}	All						0.8		V	
Address-Input Threshold (High)	V _{INH}	J		(Note 4)				3.0		V	
		K, S		(Note 4)				2.4			
Input Logic Current	I _{INL} or I _{INH}	All			0.1	10		0.1	30	μA	
Address-Input Capacitance	C _{IN}	All			3			3		pF	
DYNAMIC CHARACTERISTICS (Note 5)											
Switching Time of Multiplexers (Figure 1)	t _{TRANSITION}	All	Off	V _{IN} = 0V to 5V	700	1000		1500		ns	
Break-Before-Make Interval (Figure 2)	t _{OPEN}	All	Off	V _{IN} = 0V to 5V	100			100		ns	
Enable Turn-On Time (Figure 3)	t _{ON} (EN)	All	On	V _{EN} = 0V to 5V	0.8	1.5		2.0		μs	
Enable Turn-Off Time (Figure 3)	t _{OFF} (EN)	All	Off	V _{EN} = 0V to 5V	0.8	1		1.5		μs	
Off Isolation	O _{IRR}	All	Off	V _{EN} = 0, R _L = 200Ω, C _L = 3pF, V _S = 3V _{RMS} , f = 50kHz	70		70			dB	
Source-Off Capacitance	C _{S(OFF)}	All	Off		5					pF	
Drain-Off Capacitance	C _{D(OFF)}	MX7501 MX7503	Off		40					pF	
		MX7502	Off		20						
Source-to-Drain Capacitance	C _{S-D}	All	Off		0.5					pF	

Note 3: JN/KN versions specified for 0°C to +70°C; JQ/KQ versions for -40°C to +85°C; SQ/SE versions for -55°C to +125°C.

Note 4: A pull-up resistor, typically 1-2kΩ is required to make the J version compatible with TTL/DTL. The maximum value is determined by the output leakage current of the driver gate when in the high state.

Note 5: AC parameters are sample tested to ensure conformance to specifications.

Low-Power, Monolithic, CMOS Analog Multiplexers

ELECTRICAL CHARACTERISTICS (continued)

(V₊ = +15V, V₋ = -15V, GND = 0V, unless otherwise noted.)

PARAMETER	SYMBOL	VERSION (Note 3)	SWITCH CONDITION	TEST CONDITIONS	+25°C			OVER SPECIFIED TEMP. RANGE			UNITS
					MIN	TYP	MAX	MIN	TYP	MAX	
POWER SUPPLY											
Positive Supply Current	I ₊	All	Off	Digital Inputs = 0V	0.05	0.1	0.2	0.2	0.1	0.2	mA
Negative Supply Current	I ₋	All	Off	Digital Inputs = 0V	0.05	0.1	0.2	0.2	0.1	0.2	mA
Positive Supply Current	I ₊	All	On	Digital Inputs = 5V	0.15	0.3	0.5	0.5	0.3	0.5	mA
Negative Supply Current	I ₋	All	On	Digital Inputs = 5V	0.05	0.1	0.2	0.2	0.1	0.2	mA
Power-Supply Range for Continuous Operation	V _{OP}	All		(Note 6)	±4.5	±18					V

Note 3: JN/KN versions specified for 0°C to +70°C; JQ/KQ versions for -40°C to +85°C; SQ/SE versions for -55°C to +125°C.

Note 4: A pull-up resistor, typically 1-2kΩ is required to make the J version compatible with TTL/DTL. The maximum value is determined by the output leakage current of the driver gate when in the high state.

Note 5: AC parameters are sample tested to ensure conformance to specifications.

Note 6: Guaranteed, but not tested. Electrical Characteristics will change when power supplies other than ±15V are used.

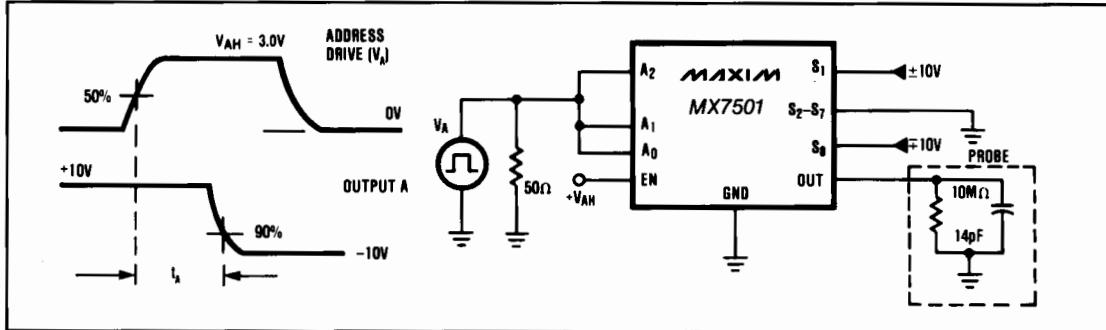


Figure 1. Transition Time vs. Logic Level (High)

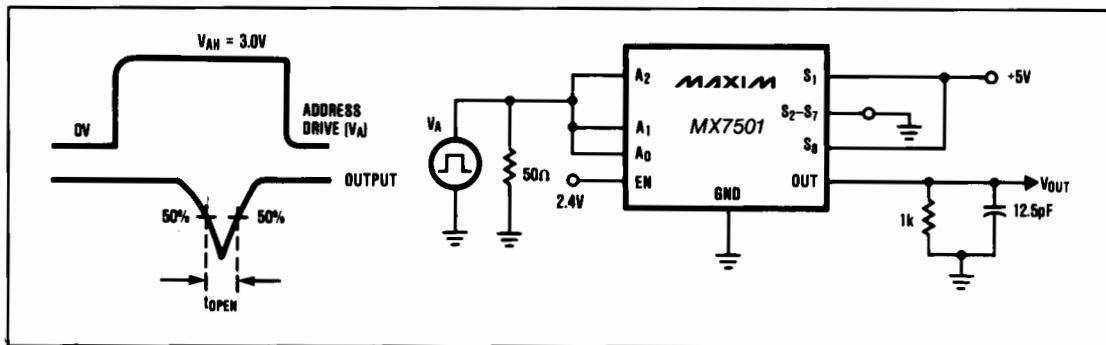


Figure 2. Break-Before-Make Interval (tOPEN)

MX7501/7502/7503

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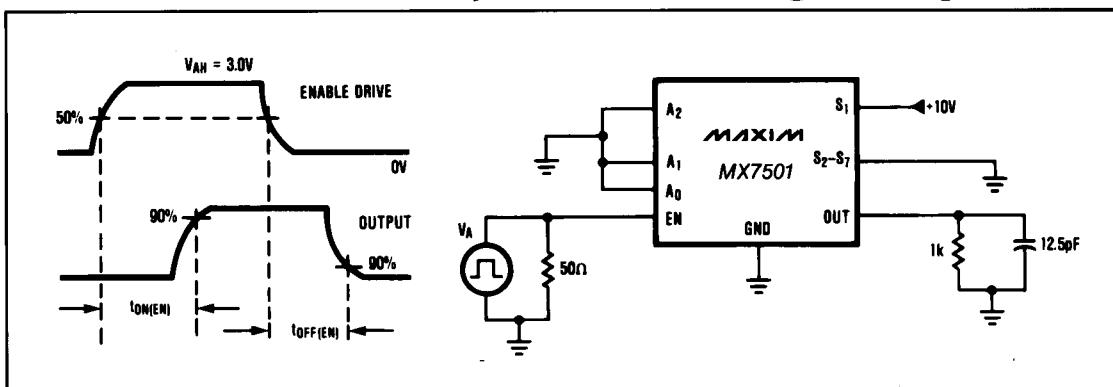


Figure 3. Enable Turn-On/Turn-Off Time

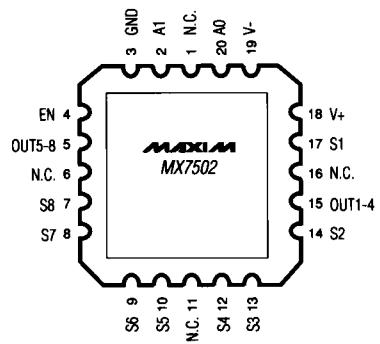
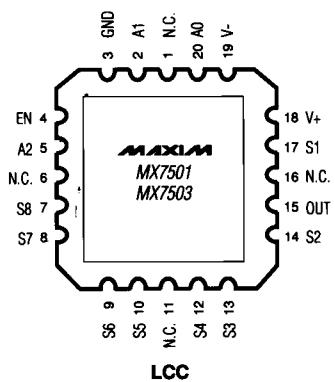
TRUTH TABLES

MX7501				
A ₂	A ₁	A ₀	EN	"ON"
0	0	0	1	1
0	0	1	1	2
0	1	0	1	3
0	1	1	1	4
1	0	0	1	5
1	0	1	1	6
1	1	0	1	7
1	1	1	1	8
X	X	X	0	None

MX7502				
A ₁	A ₀	EN	"ON"	
0	0	1	1 & 5	
0	1	1	2 & 6	
1	0	1	3 & 7	
1	1	1	4 & 8	
X	X	0	None	

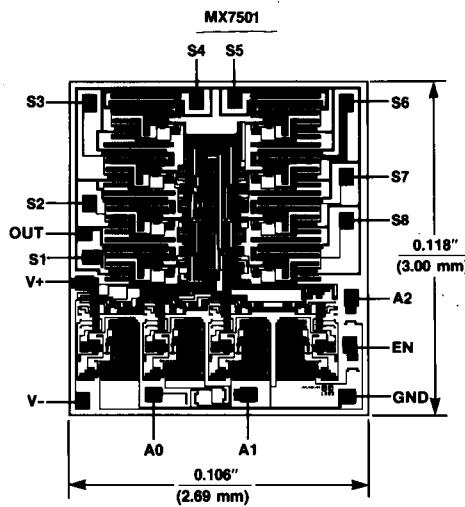
MX7503				
A ₂	A ₁	A ₀	EN	"ON"
0	0	0	0	1
0	0	1	0	2
0	1	0	0	3
0	1	1	0	4
1	0	0	0	5
1	0	1	0	6
1	1	0	0	7
1	1	1	0	8
X	X	X	1	None

Pin Configurations (continued)



Low-Power, Monolithic, CMOS Analog Multiplexers

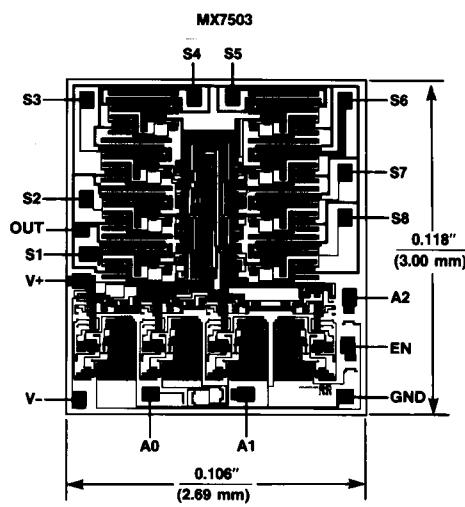
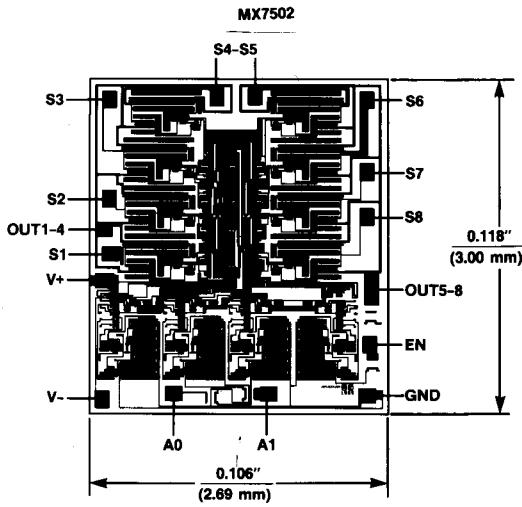
Chip Topographies



Ordering Information (continued)

PART	TEMP. RANGE	PIN-PACKAGE
MX7502JN	0°C to +70°C	16 Plastic DIP
MX7502KN	0°C to +70°C	16 Plastic DIP
MX7502C/D*	0°C to +70°C	Dice
MX7502JQ	-40°C to +85°C	16 CERDIP
MX7502KQ	-40°C to +85°C	16 CERDIP
MX7502SQ	-55°C to +125°C	16 CERDIP
MX7502SE*	-55°C to +125°C	20 LCC
MX7503JN	0°C to +70°C	16 Plastic DIP
MX7503KN	0°C to +70°C	16 Plastic DIP
MX7503C/D*	0°C to +70°C	Dice
MX7503JQ	-40°C to +85°C	16 CERDIP
MX7503KQ	-40°C to +85°C	16 CERDIP
MX7503SQ	-55°C to +125°C	16 CERDIP
MX7503SE*	-55°C to +125°C	20 LCC

* For Dice, Plastic Leadless Chip Carrier (PLCC), Ceramic Leadless Chip Carrier (LCC) and Ceramic Sidebraze (Ceramic SB), contact factory for availability.



Low-Power, Monolithic, CMOS Analog Multiplexers

Package Information

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	—	0.200	—	5.08
A1	0.015	—	0.38	—
A2	0.125	0.175	3.18	4.45
A3	0.055	0.080	1.40	2.03
B	0.016	0.022	0.41	0.56
B1	0.045	0.065	1.14	1.65
C	0.008	0.012	0.20	0.30
D1	0.005	0.080	0.13	2.03
E	0.300	0.325	7.62	8.26
E1	0.240	0.310	6.10	7.87
e	0.100	—	2.54	—
eA	0.300	—	7.62	—
eB	—	0.400	—	10.16
L	0.115	0.150	2.92	3.81

Plastic DIP
PLASTIC
DUAL-IN-LINE
PACKAGE
(0.300 in.)

21-0043A

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.060	0.100	1.52	2.54
A1	0.050	0.088	1.27	2.24
B1	0.022	0.028	0.56	0.71
B3	0.006	0.022	0.15	0.56
D/E	0.342	0.358	8.69	9.09
D1/E1	0.200	BSC	5.08	BSC
D2/E2	0.100	BSC	2.54	BSC
D3/E3	—	0.350	—	9.09
e	0.050	BSC	1.27	BSC
e1	0.015	—	0.38	—
h	0.040	REF	1.02	REF
J	0.020	REF	0.51	REF
L	0.045	0.055	1.14	1.40
L1	0.045	0.055	1.14	1.40
L2	0.075	0.095	1.91	2.41
L3	0.003	0.015	0.08	0.38

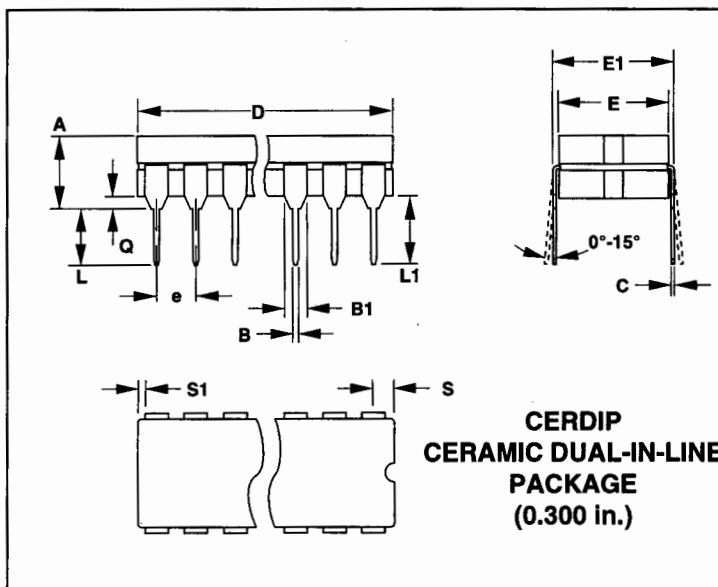
20-PIN LCC
LEADLESS CERAMIC
CHIP CARRIER

21-658A

CONTACT FACTORY FOR AVAILABILITY

Low-Power, Monolithic, CMOS Analog Multiplexers

Package Information (continued)



The technical drawing illustrates the CERDIP package with various dimensions labeled: A, D, L, Q, e, B1, B, L1, E1, E, C, S1, and S. The side view shows the package height (E1), lead width (E), lead spacing (C), and lead angle (0°-15°). The bottom view shows the chip outline and pin locations.

**CERDIP
CERAMIC DUAL-IN-LINE
PACKAGE
(0.300 in.)**

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	—	0.200	—	5.08
B	0.014	0.023	0.36	0.58
B1	0.038	0.065	0.97	1.65
C	0.008	0.015	0.20	0.38
E	0.220	0.310	5.59	7.87
E1	0.290	0.320	7.37	8.13
e	—	0.100	—	2.54
L	0.125	0.200	3.18	5.08
L1	0.150	—	3.81	—
Q	0.015	0.070	0.38	1.78
S	—	0.098	—	2.49
S1	0.005	—	0.13	—

DIM	PINS	INCHES		MILLIMETERS	
		MIN	MAX	MIN	MAX
D	8	—	0.405	—	10.29
D	14	—	0.785	—	19.94
D	16	—	0.840	—	21.34
D	18	—	0.960	—	24.38
D	20	—	1.060	—	26.92
D	24	—	1.280	—	32.51

21-0045A

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